

SURFACE MOUNT FAST RECOVERY RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
250°C / 10 seconds at terminals
- ◆ Glass passivated chip junction

Mechanical Data

Case : JEDEC DO-214AA/SMB Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

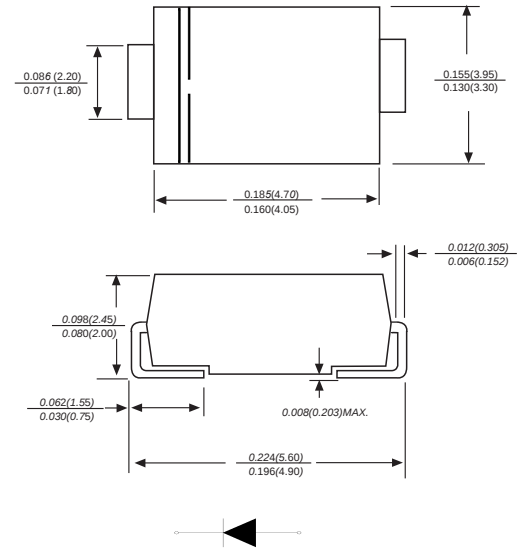
Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.003ounce, 0.093grams

DO-214AA/SMB

RoHS
COMPLIANT



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

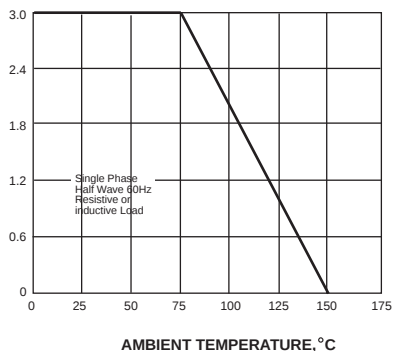
Parameter	SYMBOLS	RS5AB	RS5BB	RS5DB	RS5GB	RS5JB	RS5KB	RS5MB	UNITS
Marking Code		MDD RS5AB	MDD RS5BB	MDD RS5DB	MDD RS5GB	MDD RS5JB	MDD RS5KB	MDD RS5MB	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at TL=90℃	I _(AV)	5.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	135							A
Maximum instantaneous forward voltage at 5.0A	V _F	1.30							V
Maximum DC reverse current TA=25℃ at rated DCblocking voltage TA=125℃	I _R	10.0 150.0							μA
Maximum reverse recovery time (NOTE 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (NOTE 2)	C _J	45.0							pF
Typical thermal resistance (NOTE 3)	RθJA	48.0							℃/W
Operating junction and storage temperature range	TJ,Tstg	-55 to +150							℃

Note: 1. Reverse recovery condition $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $t_{rr}=0.25\text{A}$
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

Ratings And Characteristic Curves

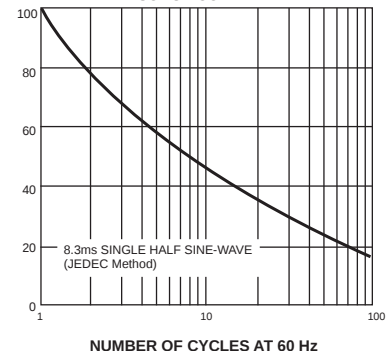
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



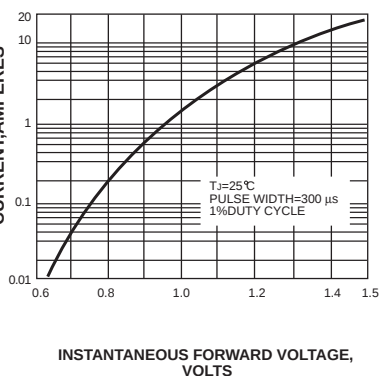
PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



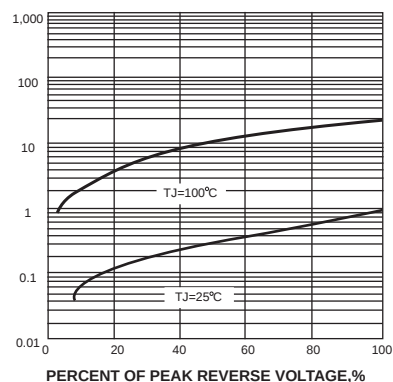
INSTANTANEOUS FORWARD
CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



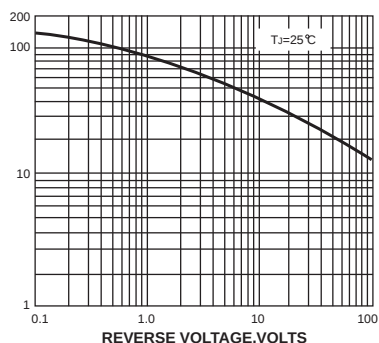
INSTANTANEOUS REVERSE CURRENT,
MICROAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



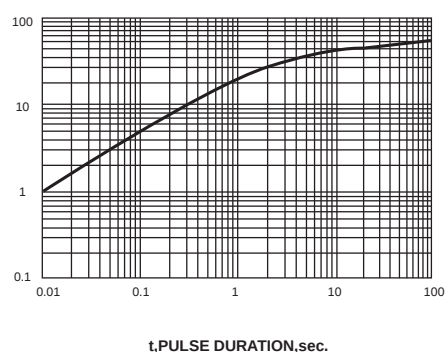
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



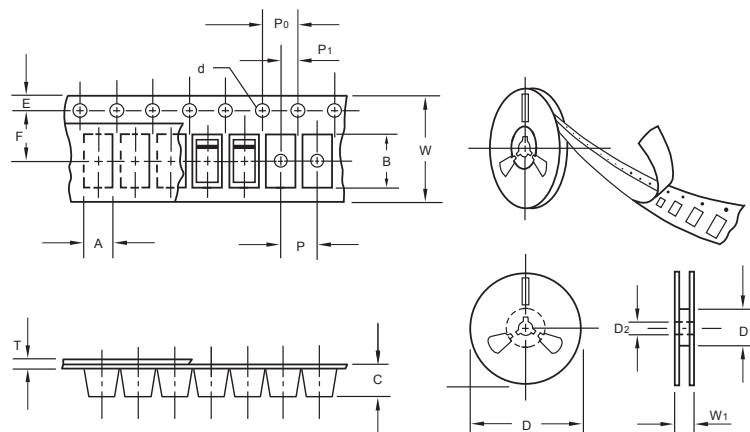
TRANSIENT THERMAL IMPEDANCE,
°C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



The curve above is for reference only.

Packing information



unit:mm

Item	Symbol	Tolerance	SMB
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.5.0
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.55
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W ₁	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMB	13"	3,000	4.0	6,000	190*190*41	330	365*365*360	48,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.8	0.110
B	2.4	0.094
C	4.6	0.181
D	2.2	0.086
E	7.0	0.276